

Form PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
MI22-1363SERIAL NO. 09/512968
Filed HerewithLIST OF ART CITED BY APPLICANT
(Use several sheets if necessary)APPLICANT
Micron Technology, Inc.FILING DATE
Filed HerewithGROUP 2858
Unknown

U.S. PATENT DOCUMENTS

*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA 00/032,184		Akram et al.			2/27/08
VN	AB 5,495,667	3/5/96	Farnworth et al.	29	843	
	AC					
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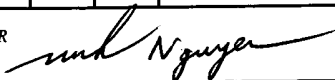
FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
	AL						
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OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

AK	Advertisement for Probe Technology from the Web Page of Interconnect Devices, Inc., 1 page
AS	Good Things Come In Small BGA/CSP Packages from the Web Page of Johnstech International, Corporation, 1 page
AT	Product Description for Test Socket Contacts from the Web Page of Johnstech International, Corporation, 1 page

EXAMINER



DATE CONSIDERED

01/26/2001

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
M122-1363SERIAL NO.
Filed HerewithLIST OF ART CITED BY APPLICANT
(Use several sheets if necessary)APPLICANT
Micron Technology, Inc.FILING DATE
Filed HerewithGROUP
Unknown

U.S. PATENT DOCUMENTS

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FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AL							
	AM							
	AN							
	AO							
	AP							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

	AR	Product Description for Double Ended Probes, B105Z Series, from the Web Page of Rika Denshi America, Inc., 1 page
	AS	Product Description for Test Centers, RM 500 Series Probes, from the Web Page of Rika Denshi America, Inc., 1 page
	AT	Product Description for Cost Effective Interconnections for High I/O Products from the Web Page of Rika Denshi America, Inc., 1 page

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U.S. PATENT DOCUMENTS

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						Yes	No
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	AN						
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OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

AR		Product Description for Ball Grid Probe B1303-C3 from the Web Page of Rika Denshi America, Inc., 1 page
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Vanh Nguyen

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U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
MI22-1363SERIAL NO.
09/512,968LIST OF ART CITED BY APPLICANT
(Use several sheets if necessary)APPLICANT
Micron Technology, Inc.FILING DATE
Filed HerewithGROUP
2858

U.S. PATENT DOCUMENTS

*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
VN	AA 4,560,216	12/24/85	Egawa			
VN	AB 4,754,555	7/5/88	Stillman			
VN	AC 5,475,317	12/12/95	Smith			
	AD					
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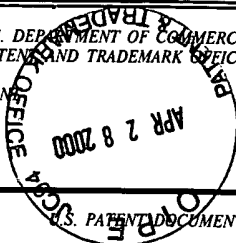
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MI22-1363SERIAL NO.
09/512,968LIST OF ART CITED BY APPLICANT
(Use several sheets if necessary)APPLICANT
Micron Technology, Inc.FILING DATE
February 24, 2000GROUP
~~Unknown~~ 2858

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
VN	AA	5,325,052	6/28/94	Yamashita			
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Mark Nguyen

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